

Part Number: XZFMG07A

SURFACE MOUNT DISPLAY

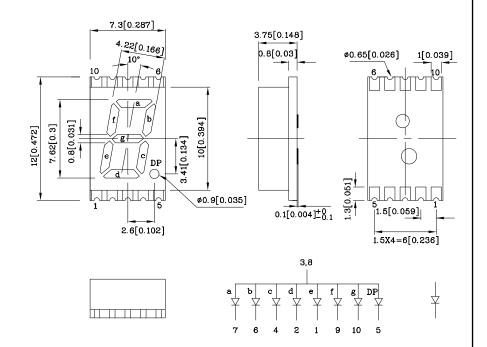
Features

- 0.3 inch digit height
- Robust package
- Low power consumption
- \bullet Standard configuration: Gray face w/ white segments
- Standard Package: 550pcs/ Reel
- MSL (Moisture Sensitivity Level): 2a
- RoHS Compliant





Package Schematics



Notes:

- 1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 2. Specifications are subject to change without notice.
- 3. The gap between the reflector and PCB shall not exceed 0.25mm.

Absolute Maximum Ratings (T _A =25°C)		Green (GaP)	Unit
Reverse Voltage	V_{R}	5	V
Forward Current	I_{F}	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	140	mA
Power Dissipation	P_{D}	62.5	mW
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	C

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T _A =25°C)		Green (GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V_{F}	2	V
Forward Voltage (Max.) (I _F =10mA)	V_{F}	2.4	V
Reverse Current (Max.) (V _R =5V)	I_R	10	μА
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λΡ	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λD	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

Part Number	Emitting Color	Emitting Material	CIE127-2007* (I _F =10mA) ucd		Wavelength CIE127-2007* nm λP	Description
			min.	typ.		
XZFMG07A	Green	GaP	1400	3490	565*	Common Anode, Rt.

560*

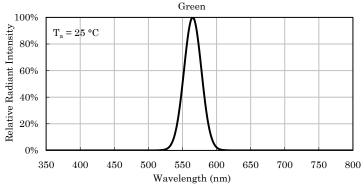
1190*

Hand Decimal.

^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Feb 22,2019

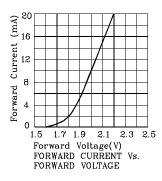


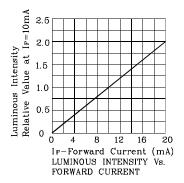


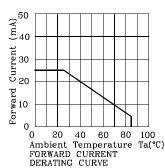


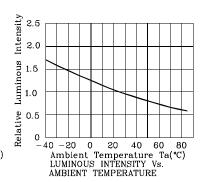
Relative Intensity Vs. CIE Wavelength

♦ Green



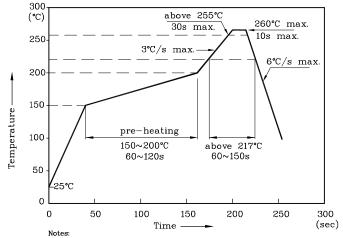






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)



- 1. All temperatures refer to the center of the package,
- measured on the package body surface facing up during reflow.

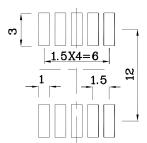
 2. Do not apply any stress to the LED during high temperature conditions.

 3. Maximum number of soldering passes: 2

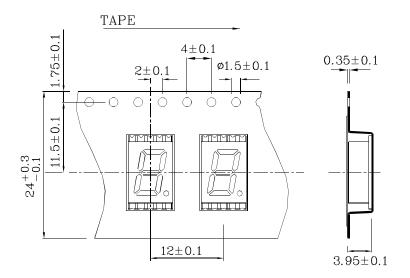




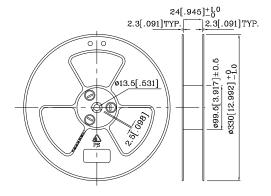
♦ Recommended Soldering Pattern (Units: mm; Tolerance: ±0.15)



❖ Tape Specification (Units:mm)



❖ Reel Dimension



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

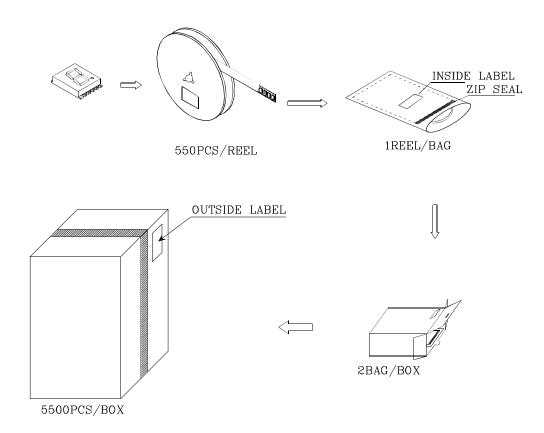
- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

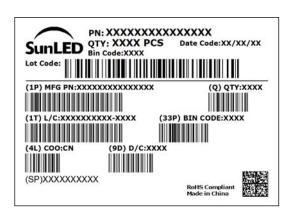
Note: Accuracy may depend on the sorting parameters.





PACKING & LABEL SPECIFICATIONS





TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
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- 7. Additional technical notes are available at https://www.SunLEDusa.com/TechnicalNotes.asp